Trade Name: LFM-70W INP 13%

1. Company Address:

Almit GmbH
Dekan-Groh-Straße 4
(DE) 64720 Michelstadt - near Frankfurt
Ph.: +49 6066 96884-0
Fax: +49 6066 96884-18

2. Validity:

This specification is specified for:
Almit-Solder-Paste LFM-70W INP 13%
Delivered by Almit GmbH to: _____

3. Diameter & Allowance:

Weight	20g	40g	80g	100g	250g
Allowance	-0, +5g				

4. Deliverable Reel Size:

Metal Name	Solidus °C	Liquidus °C	Specific Gravity
LFM-70	194	206	7.4

5. Physical Properties:

Test	Characteristics	Test Methods
Metal Content	87.0 ± 1.0	IPC-TM-650 2.2.20
Silver Chromate	pass	IPC-TM-650 2.3.33
Copper Mirror Test	pass	IPC-TM-650 2.3.32
SIR (85°C, 85%, 168hr) (Ω)	≥ $1x10^{8}$	IPC-TM-650 2.6.3.3
Corrosion Test	pass	IPC-TM-650 2.6.15
Flux materials composition	RO	J-STD 004 1.2
Quantitative Halide	L1 < 0.5%	IPC-TM-650 2.3.35
Fluorides By Spot Test	pass	IPC-TM-650 2.6.35.1

6. Characterisitcs:

Composition	Components							
	Sn	Ag	Cu	Pb	Sb	Bi		In
Standard	Rest	3.5	≤0.05	<0.05	≤0.10	0.5		8.0
Composition	Components							
	Al		As	Cd	Fe		Zn	
Standard	≤0.001		≤0.03	≤0.002	≤0.02	≤0.01	≤0.001	

7. Solder Powder Size & Distribuon :

% of Sample by Weight – Nominal Size

Type	not larger than	less than 1% larger than	at least 80% between	at most 10% less than
Type 4 (W)	40 Microns	38 Microns	20 - 38 Microns	20 Microns

8. Lot-Size: A single lot contains 500kg which is the amount of one melting.

9. Quality and Inspecon :

Inspecon items are applied to each lot as follows :

Test No.	Inspection Item	Contents	Standard	
1	Appearance	Color	Comparison with Limit Specimen	
2	Weight	Net Weight	-0 ; +5	(g)
3	Solder Powder Size	20 - 38 µm (W)	94 ≤	(wt%)
4	Metal Composition	Sn	Rest	(wt%)
		Ag	3.5 ± 0.2	(wt%)
		In	8.0 ± 0.5	(wt%)
		Bi	0.5 ± 0.1	(wt%)
5	Characteristics	Flux Content	13.0 ± 0.5	(wt%)
6		Solder Balling Test	Comparison with Limit Specimen	
7		Viscosity (Spiral type, 10rpm, 25°C) (IPC-650-2.4.34.3)	80000 ± 30000 80 ± 30	(cps) (Pa•s)
8		Solderability on Cu-Plate	Comparison with Limit Specimen	
9		Dryness	Chalk powder should be easily removed from each test specimen.	

*Straight lines of solder paste are printed on a JIS-2 type substrate then reflowed. The reflowed solder is examined with a stereo microscope at 30X magnification. No more than 2 solder balls larger than one fifth the size of the pattern gap is allowed per gap.

10. Packing:

Individual Package		Outer Package	
Unit	Packing	Unit	Packing
20g	5cc Catridge	-	Cardboard Box
40g	10cc Catridge	-	
80g	30cc Catridge	-	
100g	30cc Catridge	-	
250g	100cc Catridge	-	

11. Identification:

	Catridge	Cardboard
Name	Almit-Solder-Paste LFM-70W INP 13%	same as the left
Lot Nr.	(Ex.) 120119-9	dto.
Solder Powder Size	20 - 38 µm	dto.
Date of Mfg.	(Ex.) 19.01.2012	dto.
Net Weight	(Ex.) 20g	dto.
Maker	Nihon Almit Co. Ltd.	dto.

10. Maker Address: Nihon Almit Co. Ltd.
Almit Bldg., 2-14-2 Yayoicho, Nakano-ku, Tokyo, Japan

11. In case of changing this specification it should be accepted by:
Signature_____ Date_____

12. This product is manufactured, using all guaranteed materials according to the legal law regulations.

13. Shelf Life:
Up to
3 month from the manufactured date (lot number).